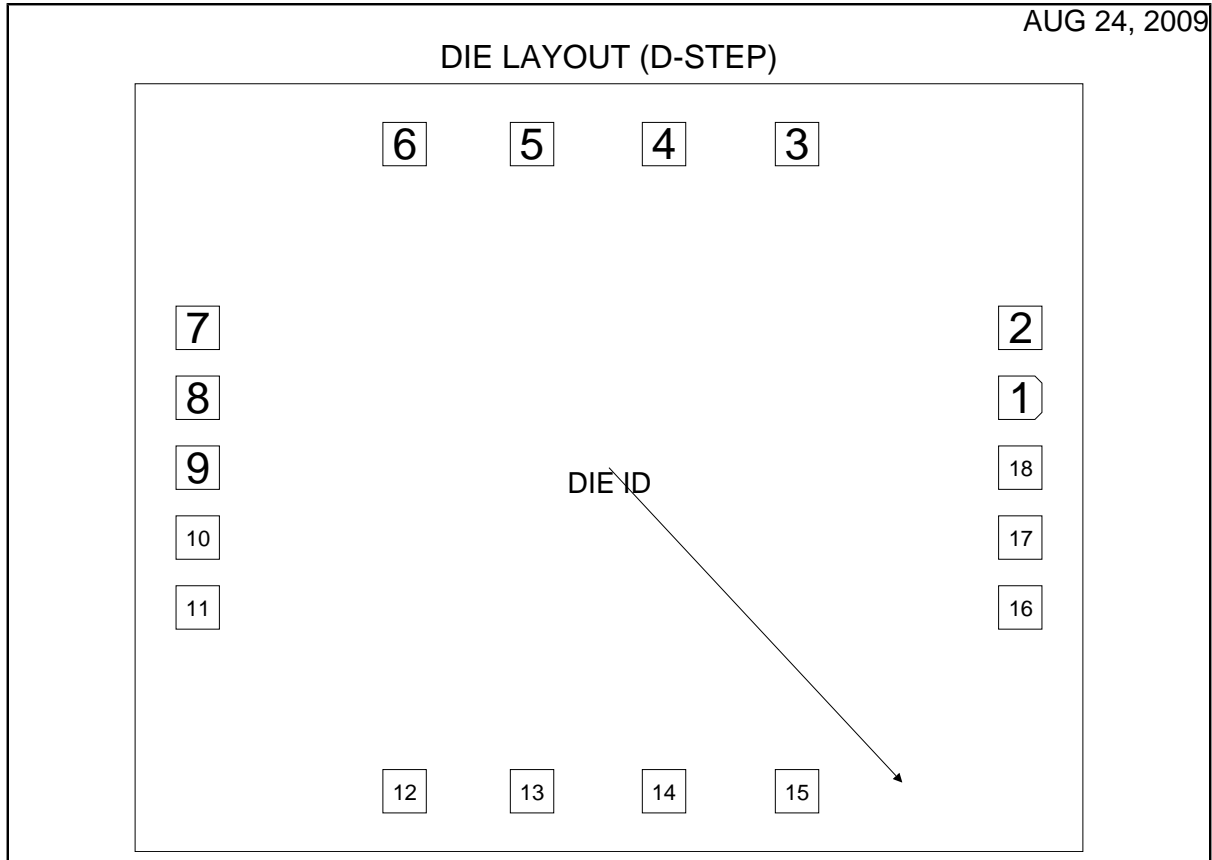


DS90C031 MDR MCD3040A
LVDS QUAD CMOS DIFFERENTIAL LINE DRIVER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DS90C031	Bond Pad Opening Size (min)	91.76µm x 91.92µm
Die Step	D	Bond Pad Metalization	0.5%CU,1%SI/2M
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	2006.6µm x 1625.6µm 79.0mils x 64.0mils	Back Side Connection	Floating or GND
Thickness	304.8µm Nominal		
Min Pitch	148.00µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(D-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
DIN 1	1	148	-871	92	x	92
DOUT 1+	2	296	-871	92	x	92
DOUT 1-	3	685	-398	92	x	92
EN	4	685	-117	92	x	92
DOUT2-	5	685	163	92	x	92
DOUT2+	6	685	433	92	x	92
DIN2	7	296	871	92	x	92
GND	8	148	871	92	x	92
GND	9	0	871	92	x	92
DIN3	10	-148	871	92	x	92
DOUT3+	11	-296	871	92	x	92
DOUT3-	12	-685	433	92	x	92
EN*	13	-685	163	92	x	92
DOUT4-	14	-685	-117	92	x	92
DOUT4+	15	-685	-398	92	x	92
DIN4	16	-296	-871	92	x	92
VCC	17	-148	-871	92	x	92
VCC	18	0	-871	92	x	92

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Notes

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